

ABSTRACT OF THE DISCLOSURE

There is provided a semiconductor package that includes a metal plate, and a wiring substrate having an insulating substrate, signal wiring layer formed on one surface of the insulating substrate, and a ground plane formed integrally on other surface of the insulating substrate, whereby a surface of the ground plane side of the wiring substrate is adhered onto the metal plate. The signal wiring layer is constructed by a wiring line portion and a connection pad portion whose width is thicker than a width of the wiring line portion, and non-forming portion is provided in portion of the ground plane, which corresponds to the connection pad portion. In addition, a recess portion may be formed in portion of the metal plate, which correspond to the non-forming portion.